

Centralised Unit (CU)

The gNB is the central unit that manages the RRC and PDCP layers and consists of a CU and one or more DUs. The CU connects to DUs using Fs-C for the control plane and Fs-U for the user plane. It can support multiple DUs and gNBs. The O-RAN architecture provides flexibility in distributing protocol stacks between the CU and DUs based on midhaul capacity and network design.



List of RIC vendors tested with the AWTG

CU software VMware, CG.

List of DU vendors tested with the AWTG

CU software Mavenir, Fujitsu, Radisys.

List of 5G Core vendors tested with

the AWTG CU Software

Affirmed, Mavenir, Spirent,

Viavi, Amantya, Druid,

Ericsson, Nokia, IPLook,

Capgemini.

Number of DUs/vDUs supported by the AWTG

CU Software 4 DUs per CU.

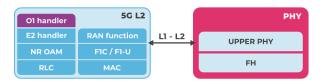
Minimum Hardware x86 Intel Xeon Gold 24 Cores CPU

NIC: Intel 10GE (Quad)

x1 TB SSD

Distribution Unit (DU)

This distributed unit, located near the RU, handles the RLC, MAC, and parts of the physical layer. It includes some eNB/gNB functions based on the functional split option and is controlled by the CU. The unit also optimizes network performance and reduces latency for end-users, ensuring efficient communication and service quality.



NIC/Hardware Acceleration Cards Required X810 NIC 10G

for FH & transport (E810XXVDAG2P5), ACC100 Mount Bryce.

Compatible Sync LLS-C1, C2, C3, C4,

compatible with DU LLS-C1/3 validated.

Tested Vendors for RU, CU, RIC MTI, Foxconn,

Benetel, Fujitsu, Viavi O-RU.

Upper PHY Information based on x86 FlexRAN 22.11.

Fronthaul Category Supported 7.2A or 7.2B.

Number of Supported RUs 4.

Supported Scheduling Algorithms Round Robin & QoS.

Fault Management System Supported via O1 interface using Netconf/yang based.

Minimum Hardware x86 Intel Xeon Gold 24 Cores CPU,
ACC100 Mount Bryce for FEC offload, NIC Intel E810
XXVDA4 (Quad), x1 TB SSD, x1 Intel Dual Port 10GbE BASE-T.

SAWTG CU & DU Requirements

2,000 users at CU-CP.	Number of connected users	DU 512 users.
Includes any SPF required for the CU.	COTS Hardware Versions	Includes any SPF needed for the DU.
Varies by server model.	Power Requirements	Varies by server model.
XNAP, FIAP, NGAP, E2, O1.	Supported Interfaces	E2, F1, Fronthaul, O1.
Uses Kubernetes K8 PODs.	Containerisation/Virtualisation	Uses Kubernetes K8 PODs.
3GPP Release 15/16 (including CUPS).	3GPP Compliance	3GPP Release 15/16.
28.552 PM counters pegged.	Monitored KPIs	28.552 PM counters supported.
CU-UP 5Gbps, 512 bearers.	Load Capacity	DU Gbps, 512 UEs.
CU-UP 5Gbps 512 bearers, 4 CU-UP per CU-CF	P. Max UL/DL Throughput	DU 5Gbps.

ORAN specifications where AWTG CU & DU is complaint to

O-RAN.WG5.IOT.O-v05.00 O-RAN.WG3.E2AP-v02.00 O-RAN.WG5.MP.O-v02.00
O-RAN.WG3.E2GAP-v02.00 O-RAN-WG3.E2SM-v02.00 O-RAN.WG5.IOT.O-v05.00
O-RAN-WG3.E2SM-KPM- v02.00 O-RAN-WG3.E2SM-RC-v01.00 O-RAN.WG1.O1-Interface-v04.00

While the specified minimum hardware requirement is an x86 Intel Xeon Gold 24 cores CPU for both the DU & CU, it is important to note that for deployments involving x4 RUs, the actual minimum CPU requirement is 32 cores.

The outlined configuration serves as a general baseline, but specific client requirements, especially for higher capacity deployments, may necessitate hardware specifications beyond those listed. Additionally, other CPU types may be deployed depending on the use case and required performance SLA.

Clients are advised to consult with our technical team to ensure their deployment configurations meet the necessary performance and scalability criteria.

SAWTG CU & DU features



Standards Support

AWTG CU & DU supports the 3GPP Rel-15 with Rel-16 roadmap using O-RAN architecture.



Interface Flexibility

Supports various 3GPP interfaces, including options for distributed or integrated AWTG CU & DU and multiple RAN splits (2, 6, 7.x, 8).



Scalability

Designed to scale capacity based on user throughput and available processing cores.



Reference Solution

Provides a pre-integrated AWTG CU & DU with partner's Radio Units, validated in end-to-end setups for key scenarios and capacity.



xApp Integration

Compatible with O-RAN defined & proprietary E2SM, supporting integration of xApps with RIC, CU & DU.



Roadmap for Future Releases

Established roadmap to support upcoming 3GPP releases, new features, O-RAN use cases, and interfaces.



Development Process

Implements CI/CD for efficient AWTG CU & DU software development.

NWTG RU Eco System

AWTG L2/L3 SW

Intel Xeon x86 uArch

(SPR-EE, IceLake,

Cascadelake, Skylake)

NXP SOC (LX2160,

2088/2, LS1046)

(ARM uArch)

ARM SOC

Octasic ARM uArch

Marvell ARM uArch

PHY SW

Intel FlexRAN L1

Phluido PHY L1

Nvidia PHY L1

ITRI PHY LI

Vicinity PHY L1

Qualcomm PHY L1

ArrayCom PHY L1

CommAgility PHY L1

Synergy PHY L1

-5......

Picocom PHY L1

Octasic PHY L1

Core NW

AWTG core

Nokia, Ericsson,

Intel-FlexCore, Astri,

Iplook, open-NGC,

Affirmed

ODM Partner

Supermicro, Dell,

Foxconn / Asus

Advantech, HPE

CIG, Arcadyan, Askey

T&W, Foxconn

Compal, Alpha/Delta

UE/Test UE

AWTG UESim

(for PHY by-pass)

Samsung - S20, S21, S22, Tab

Oneplus - Nord, CE, 9pro, 10

HTC U20

Huawei xMate 20. 30.

P40, X55 CPE

LG V50; QC x55

Viavi TM500, TMLite

Simnovous TestUE

RU Partner

Foxconn (Sub-6GHz)

Benetel (Sub-6GHz)

ITR/ALPHA (Sub-6GHz)

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Viavi oRU (Sub-6GHz, mmW)

WNC* (Sub-6GHz)

Baicells (Sub-6GHz)

Qualcomm (mmWave)

Ankiton (Sub-6GHz)

Octasic SOC + RF (Sub6-GHz)

CommScope (mmWave)

MTI (B3, FDD)

SDR (B210)

ADI (Sub-6GHz)

LiteON* (Sub-6GHz)

SDR (N310)

CIG (Sub-6GHz)

Vaitel (Sub-6GHz)

Cablefree (Sub-6GHz)